



AOS Semiconductor Product Reliability Report

AOTF260L, rev B

Plastic Encapsulated Device

ALPHA & OMEGA Semiconductor, Inc

www.aosmd.com

Jan. 2018

This AOS product reliability report summarizes the qualification result for AOTF260L. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that AOTF260L passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

I. Reliability Stress Test Summary and Results

| Test Item | Test Condition | Time Point | Total Sample Size | Number of Failures | Reference Standard |
|---------------------------|---|---------------------------|-------------------|--------------------|--------------------|
| HTGB | Temp = 150°C , Vgs=100% of Vgsmax | 168 / 500 / 1000 hours | 924 pcs | 0 | JESD22-A108 |
| HTRB | Temp = 150°C , Vds=80% of Vdsmax | 168 / 500 / 1000 hours | 924 pcs | 0 | JESD22-A108 |
| HAST | 130°C , 85%RH, 33.3 psia, Vds = 80% of Vdsmax | 96 hours | 693 pcs | 0 | JESD22-A110 |
| H3TRB | 85°C , 85%RH, Vds = 80% of Vdsmax | 1000 hours | 693 pcs | 0 | JESD22-A101 |
| Autoclave | 121°C , 29.7psia, RH=100% | 96 hours | 924 pcs | 0 | JESD22-A102 |
| Temperature Cycle | -65°C to 150°C , air to air, | 1000cycles | 924 pcs | 0 | JESD22-A104 |
| HTSL | Temp = 150°C | 1000 hours | 693 pcs | 0 | JESD22-A103 |
| IOL | Δ Tj = 100°C | 8572 cycles | 693 pcs | 0 | AEC Q101 |
| Resistance to Solder Heat | Temp = 270°C | 15 seconds | 30 pcs | 0 | JESD22-B106 |

Note: The reliability data presents total of available generic data up to the published date.

II. Reliability Evaluation

FIT rate (per billion): 1.91

MTTF = 59839 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

Failure Rate = $\text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)] = 1.91$

MTTF = $10^9 / \text{FIT} = 59839$ years

Chi² = Chi Squared Distribution, determined by the number of failures and confidence interval

N = Total Number of units from burn-in tests

H = Duration of burn-in testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [**Af**] = $\text{Exp} [Ea / k (1/Tj u - 1/Tj s)]$

Acceleration Factor ratio list:

| | 55 deg C | 70 deg C | 85 deg C | 100 deg C | 115 deg C | 130 deg C | 150 deg C |
|-----------|------------|-----------|-----------|-----------|-------------|-------------|-----------|
| Af | 259 | 87 | 32 | 13 | 5.64 | 2.59 | 1 |

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

Tj u = The use junction temperature in degree (Kelvin), K = C+273.16

k = Boltzmann's constant, $8.617164 \times 10^{-5} \text{eV} / \text{K}$